



7/19/2012

**RELIABILITY MONITOR REPORT
FOR**

Epson SiGe HBT 0.35 μ m BiCMOS (MB3)

MAXIM Integrated Products

**120 San Gabriel Dr.
Sunnyvale, CA 94086**

**This Report was prepared by
Maxim Reliability Engineering**

Summary:

The data in the tables that follow was generated as the result of an on-going Process Reliability Monitor. The specific products in this process monitor are:

TX27YETH+

The calculated failure rate for devices using this process is:

FAILURE RATE: MTTF (YRS): 2976 QUANTITY: 80 FAILS: 0 FITS: 38.4

The parameters used to calculate this failure rate are as follows:

Cf: 60% Ea: 0.7 Tu: 25 °C

The reliability data follows and in this section is the detailed reliability data by stress. The reliability data section includes the latest data available. This report covers data between 7/1/2011 and 6/30/2012 .

Process Information:

Process Description: Epson SiGe HBT 0.35µm BiCMOS (MB3)

OPERATING LIFE

DESCRIPTION	DATE CODE	TEST VEHICLE	CONDITION	READPOINT	QUANTITY	FAILS	LOT NO.
HIGH TEMP OP LIFE	1135	TX27YETH+	135C	192 HRS	80	0	E21W8A028B
Total:						0	

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